





Features & Benefits

-  High shear strength
-  Long open time
-  Reduced hazards SDS
-  High temperature resistance following low temperature cure

Description

PERMABOND® ET5424 is a two-part epoxy adhesive, designed primarily for the aerospace industry. ET5424 has excellent temperature resistance following a low temperature cure, which makes it suitable for powder coat baking. The adhesive has reduced hazards on the SDS allowing for a safer working environment. ET5424 has an extended cure time so it can be used on large bond areas and in batch production processes.

ET5424 meets the requirements of ECSS-Q-ST-70-02C (thermal vacuum outgassing test for the screening of space materials).

Physical Properties of Uncured Adhesive

	ET5424 A-side	ET5424 B-side
Chemical composition	Epoxy Resin	Modified Amine
Appearance	Grey Paste	Black Gel
Viscosity @ 25°C	245,000 mPa.s (cP) Thixotropic	1,700 mPa.s (cP) Thixotropic
Specific gravity	1.41	1.01

Typical Curing Properties

Mix ratio	4:1 by volume 100:18 by weight
Maximum gap fill	3 mm 0.12 in
Usable / pot life @23°C	10g: 4 hours
Working Strength	23°C: 24 hours
Full cure	23°C: 3-5 days 66°C: 1 hour

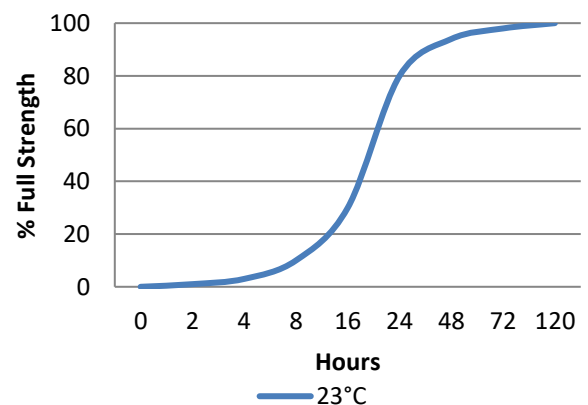
Typical Performance of Cured Adhesive

Shear strength* (ISO4587) Cured at 23°C for 5 days	Aluminium: 22-27 N/mm ² (3190-3916psi) Mild Steel: 20-25 N/mm ² (2900-3626psi) Stainless Steel: 24-29 N/mm ² (3480-4206psi) Carbon Fibre: >20 N/mm ² **SF (>2900psi)
Shear strength* (ISO4587) Cured at 66°C for 1 hour	Aluminium: 25-30 N/mm ² (3625-4351psi) Mild Steel: 21-26 N/mm ² (3046-3771psi) Stainless Steel: 28-32 N/mm ² (4061-4641psi) Carbon Fibre: >23 N/mm ² **SF (>3336psi) FRP Glass/Epoxy: >21 N/mm ² **SF (>3046psi)
Floating Roller Peel Strength (aluminium) (ISO4578)	Cured 5 days @ 23°C: 70-100 N/25mm (16-23 PIW)
Hardness (ISO868)	>80 Shore D
Thermal Conductivity (ISO 8302)	0.46 W/(m.K)
Tg (DMA, tan δ peak)	182°C (360°F)

*Strength results will vary depending on the level of surface preparation and gap.

**SF Denotes substrate failure

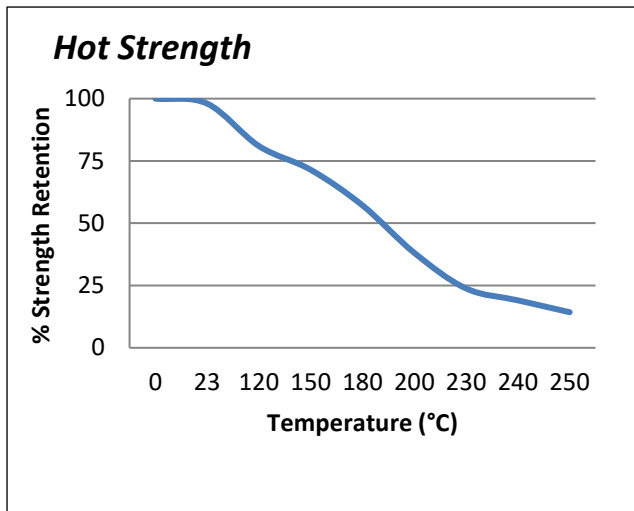
Strength Development



Graph shows typical strength development of bonded components. An increase of 8°C in temperature will halve the cure time. Lower temperatures will result in a slower cure time.

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"Hot strength" shear strength. Fully cured specimens conditioned to pull temperature for 30 minutes before testing at temperature.

ET5424 can withstand higher temperatures for brief periods (such as for paint baking and wave soldering processes) providing the joint is not unduly stressed. The minimum temperature the cured adhesive can be exposed to is -55°C (-67°F) depending on the materials being bonded.

Additional Information

This product is not recommended for use in contact with strong oxidizing materials. Information regarding the safe handling of this material may be obtained from the safety data sheet.

Users are reminded that all materials, whether innocuous or not, should be handled in accordance with the principles of good industrial hygiene.

This Technical Datasheet (TDS) offers guideline information and does not constitute a specification.

Storage & Handling

Storage Temperature	5 to 25°C (41 to 77°F)
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Surface Preparation

Surfaces should be clean, dry and grease-free before applying the adhesive. Use a suitable solvent (such as acetone or isopropanol) for the degreasing of surfaces. Some metals such as aluminium, copper and its alloys will benefit from light abrasion with emery cloth (or similar), to remove the oxide layer.

Directions for Use

1. Measure 100 parts resin to 18 parts hardener by weight. Mix thoroughly taking care not to entrap air. Adhesive can be applied and mixed by automated dispensing equipment.
2. Apply material to one of the substrates.
3. Join the parts. Parts must be joined within the usable pot life of mixing the two epoxy components.
4. Large quantities and/or higher temperature will decrease the usable life or pot life.
5. Apply pressure to the assembly by clamping until handling strength is obtained.
6. Full cure will be obtained after 3-5 days at 23°C (77°F). Heat can be used to accelerate the curing process.

NB. Exercise caution when mixing large quantities due to exothermic reaction.

Video Links

Surface preparation:

<https://youtu.be/8CMOMP7hXjU>



Two-part epoxy directions for use:

<https://youtu.be/GRX1RyknYqc>



www.permabond.com

• UK: 0800 975 9800

• General Enquiries: +44 (0)1962 711661

• US: 732-868-1372

• Asia: + 86 21 5773 4913

info.europe@permabond.com

info.americas@permabond.com

info.asia@permabond.com

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